IPC ASSOCIATION ELECTRONIC	© Copyright 200	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All right international and Pan-American copyright conventions.		Il rights reserved untions.	nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information			
upplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
nsemi											2025-07-06				
Contact N	Name	Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-	Env-Stewards		Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr It		em Number Mfr Item Name				Effective Date		on 1	Manufacturing Site		W	eight*	UOM	Unit Type
		LM2576D2TR4-012G ANA 12		ANA 12V 3A PWI	NA 12V 3A PWR SW REG		2025-07-06		1	MY1		10	517.91	mg	Each
Ianufa	ncturing Process Inform							•						•	·
	8		•		-STD-020 MSL	Rating	Peak Process Body Temper					T		er of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30		second	s 3		
omments															
	naximum time at peak temper														
or more	information regarding mater	rial composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content with the supplier of the identified part, the terms and capany's remedies for issues that arise regarding information in the content of t	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	851.27	mg	В	Nickel (Ni)	7440-02-0		2.5538	mg
			Supplier	Copper (Cu)	7440-50-8		848.7162	mg
Mold Compound-Black	727.25	mg		Epoxy resin	proprietary data		50.9075	mg
			Supplier	Phenolic Resin	Proprietary Data		21.8175	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		72.725	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		578.1638	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg